



Material Content Data Sheet



Sales Product Name	TLE7243SL			Issued		28. August 2013		
MA#	MA000982076							
Package	PG-SSOP-24-7			Weight*		147.14 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.128	3.49	3.49	34853	34853
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		106	
	non noble metal	zinc	7440-66-6	0.062	0.04		423	
	non noble metal	iron	7439-89-6	1.245	0.85		8464	
	non noble metal	copper	7440-50-8	50.568	34.37	35.27	343671	352664
wire	noble metal	gold	7440-57-5	0.769	0.52	0.52	5224	5224
encapsulation	organic material	carbon black	1333-86-4	0.171	0.12		1160	
	plastics	epoxy resin	-	7.854	5.34		53377	
	inorganic material	silicondioxide	60676-86-0	77.344	52.55	58.01	525648	580185
leadfinish	non noble metal	tin	7440-31-5	1.680	1.14	1.14	11416	11416
plating	noble metal	silver	7440-22-4	0.365	0.25	0.25	2482	2482
glue	plastics	acrylic resin	-	0.426	0.29		2899	
	noble metal	silver	7440-22-4	1.512	1.03	1.32	10277	13176
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com